

Notice of References Cited	Application/Control No. 09/652,216	Applicant(s)/Patent Under Reexamination JIANG ET AL.	
	Examiner Evan T. Pert	Art Unit 2829	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-6,406,938	06-2002	Rodenbeck et al.	438/108
	C	US-6,061,267	05-2000	Houston, Theodore W.	365/154
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NON-PATENT DOCUMENTS

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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.